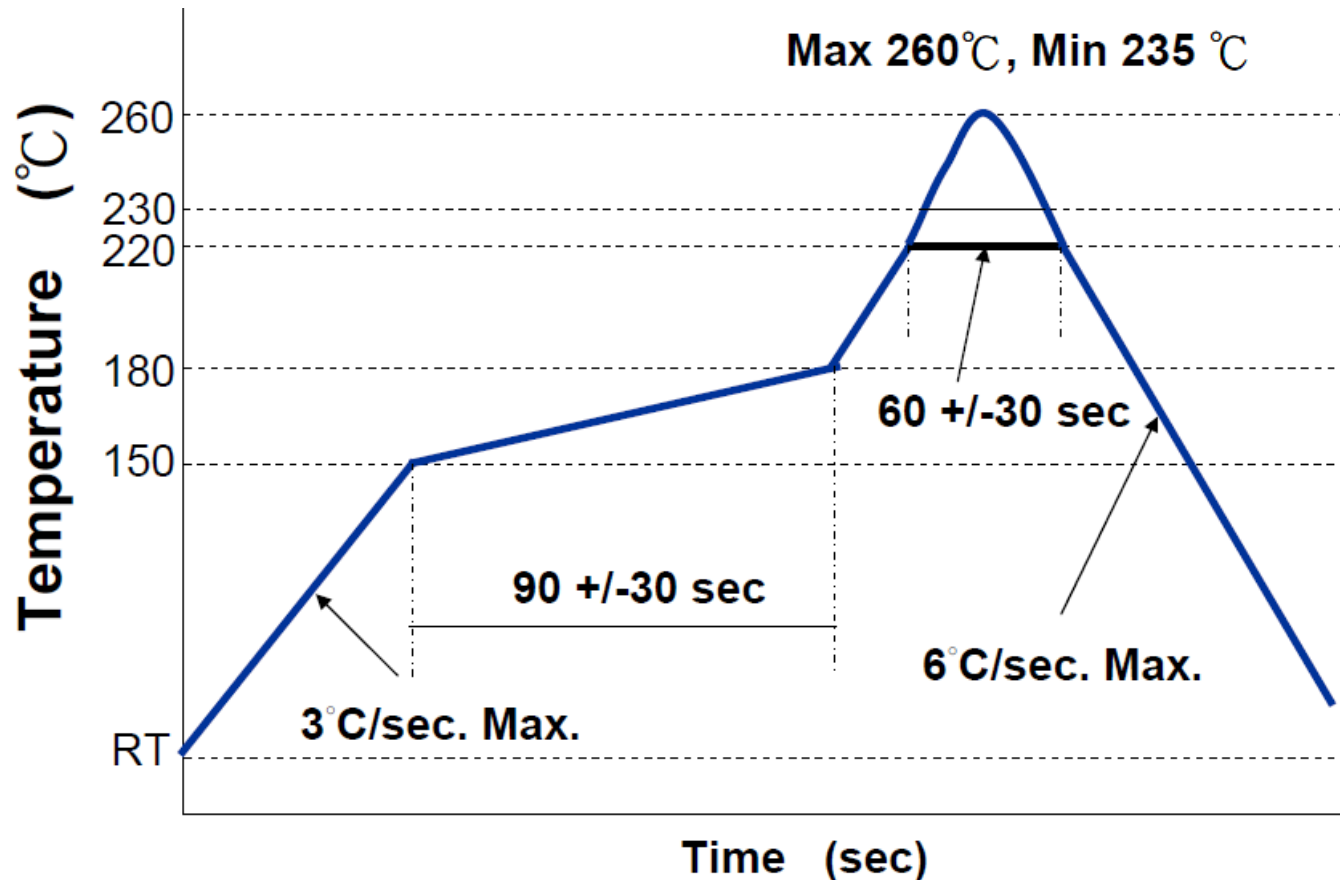


Lead-free Reflow Profile Guideline



- Reflow profile guideline for SnAgCu Pb-free solder paste.
- Reflow temperature is defined at package top.
- TI recommends following the solder paste supplier's reflow profile to optimize flux activity and also to achieve proper melting temperatures of the alloy within the guidelines of J-STD-020D.